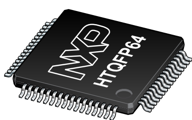

SOT855-6

HTQFP64, thermal enhanced thin quad flat package; 64 terminals, 0.5 mm pitch, 10 mm x 10 mm x 1 mm body; exposed die pad

28 January 2022 Package information

1 Package summary

Package type descriptive code	HTQFP64
Package style descriptive code	HTQFP (thermal enhanced thin quad flat package)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	14-12-2021
Manufacturer package code	98ASA01609D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	10	-	mm
package width	-	10	-	mm
seated height	1	1.1	1.2	mm
package height	0.95	1	1.05	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	64	-	

2 Package outline

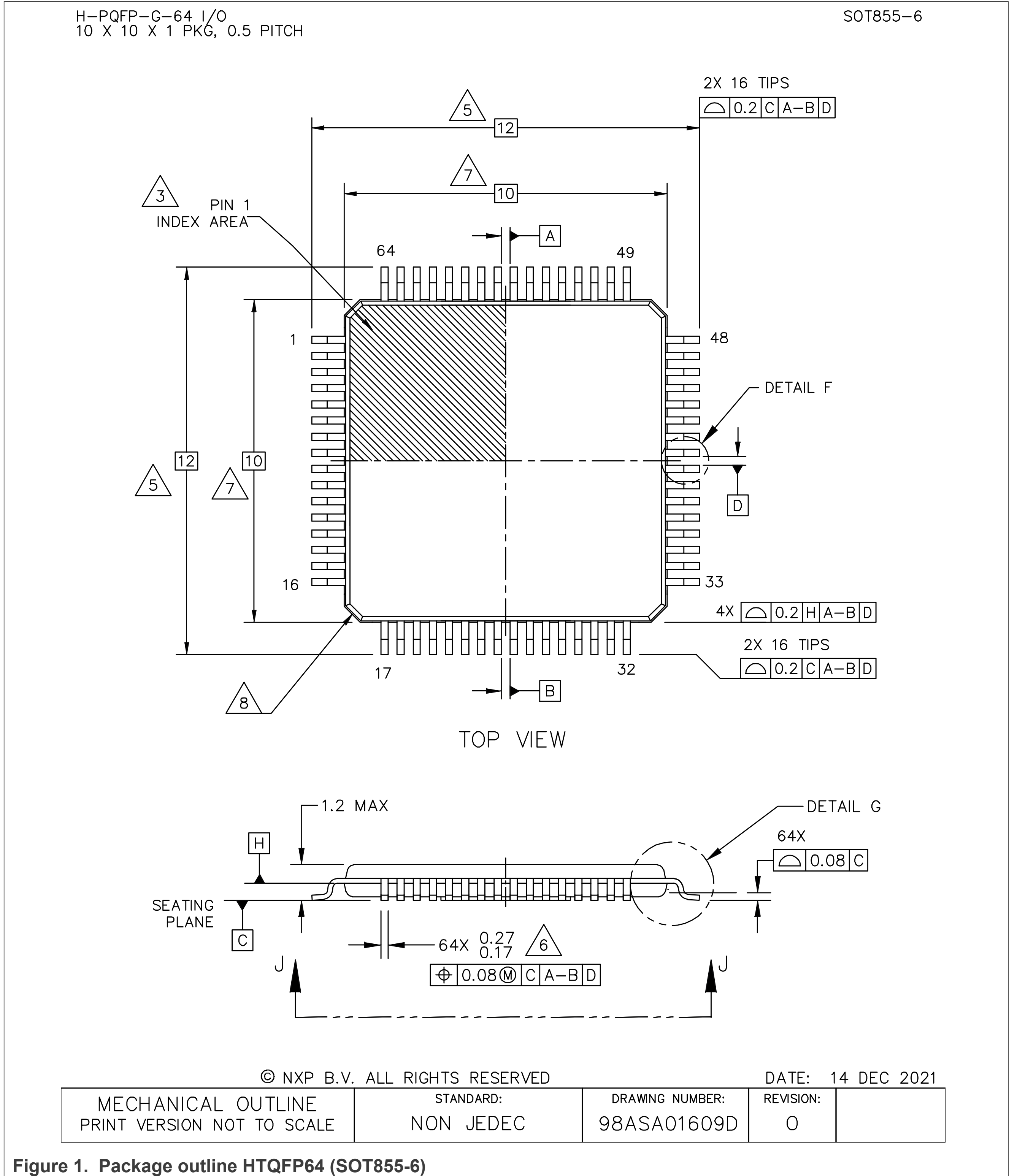

Figure 1. Package outline HTQFP64 (SOT855-6)

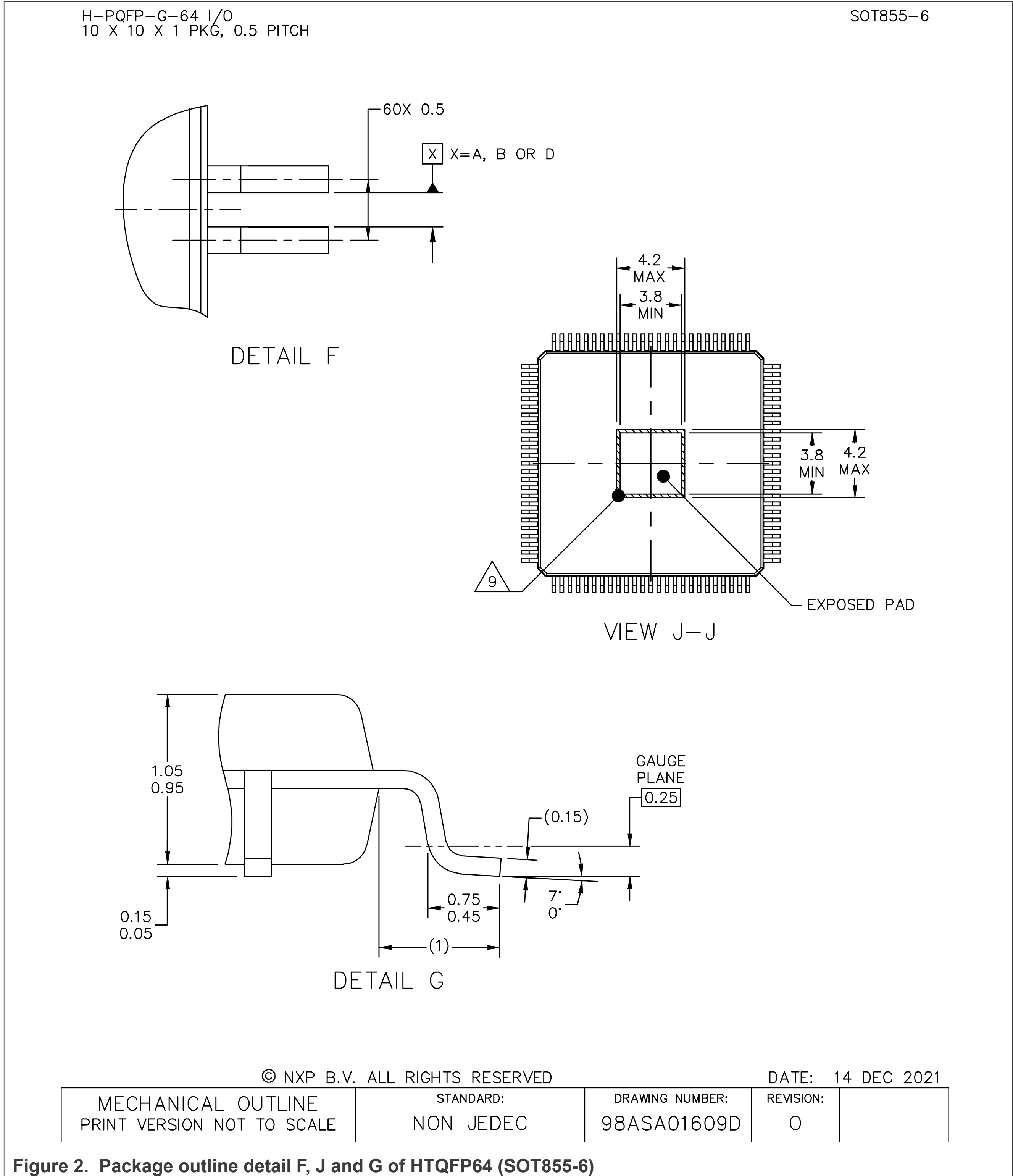

Figure 2. Package outline detail F, J and G of HTQFP64 (SOT855-6)

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3 Soldering

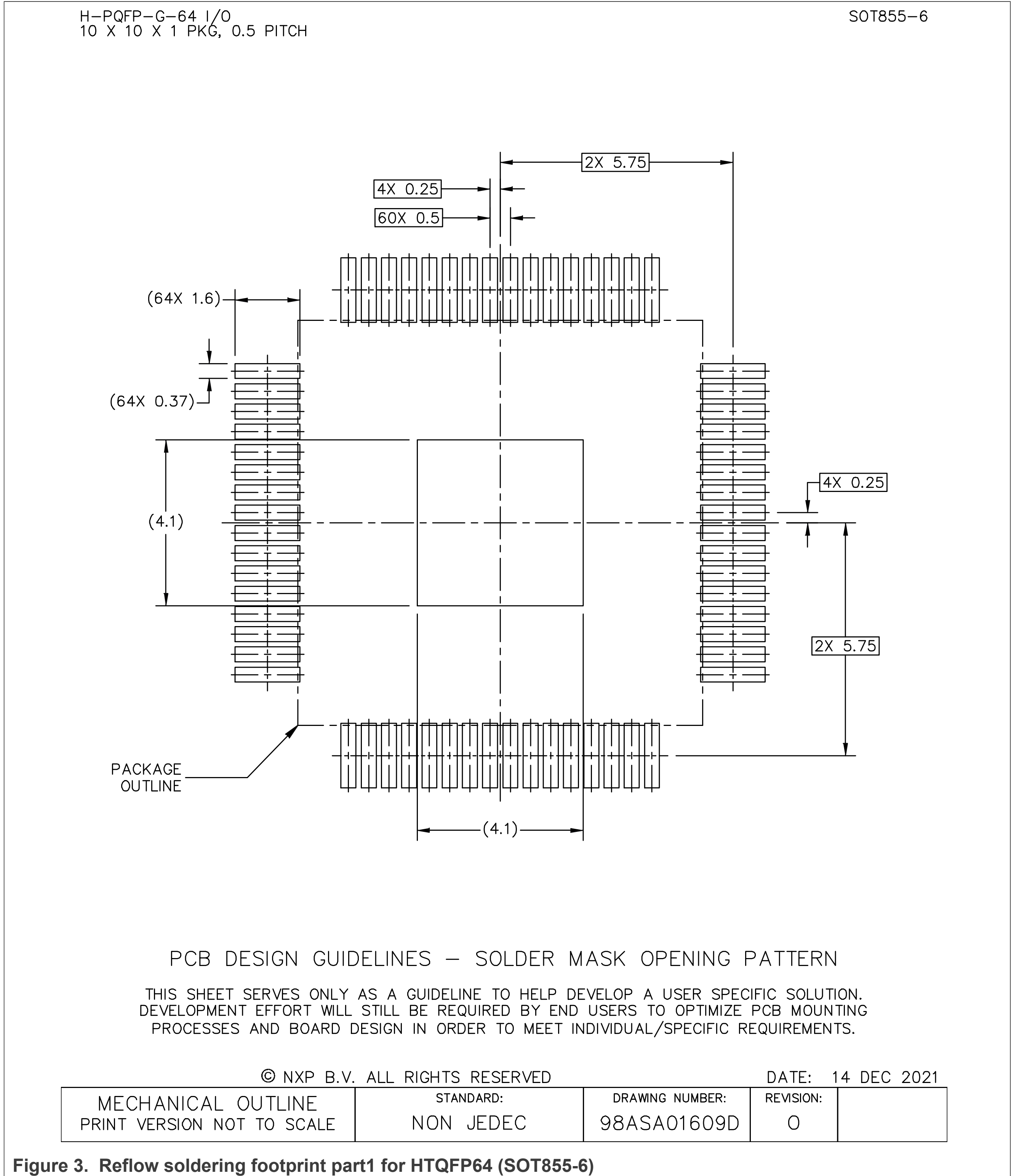

Figure 3. Reflow soldering footprint part1 for HTQFP64 (SOT855-6)

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HTQFP64, thermal enhanced thin quad flat package; 64 terminals, 0.5 mm pitch, 10 mm x 10 mm x 1 mm body; exposed die pad

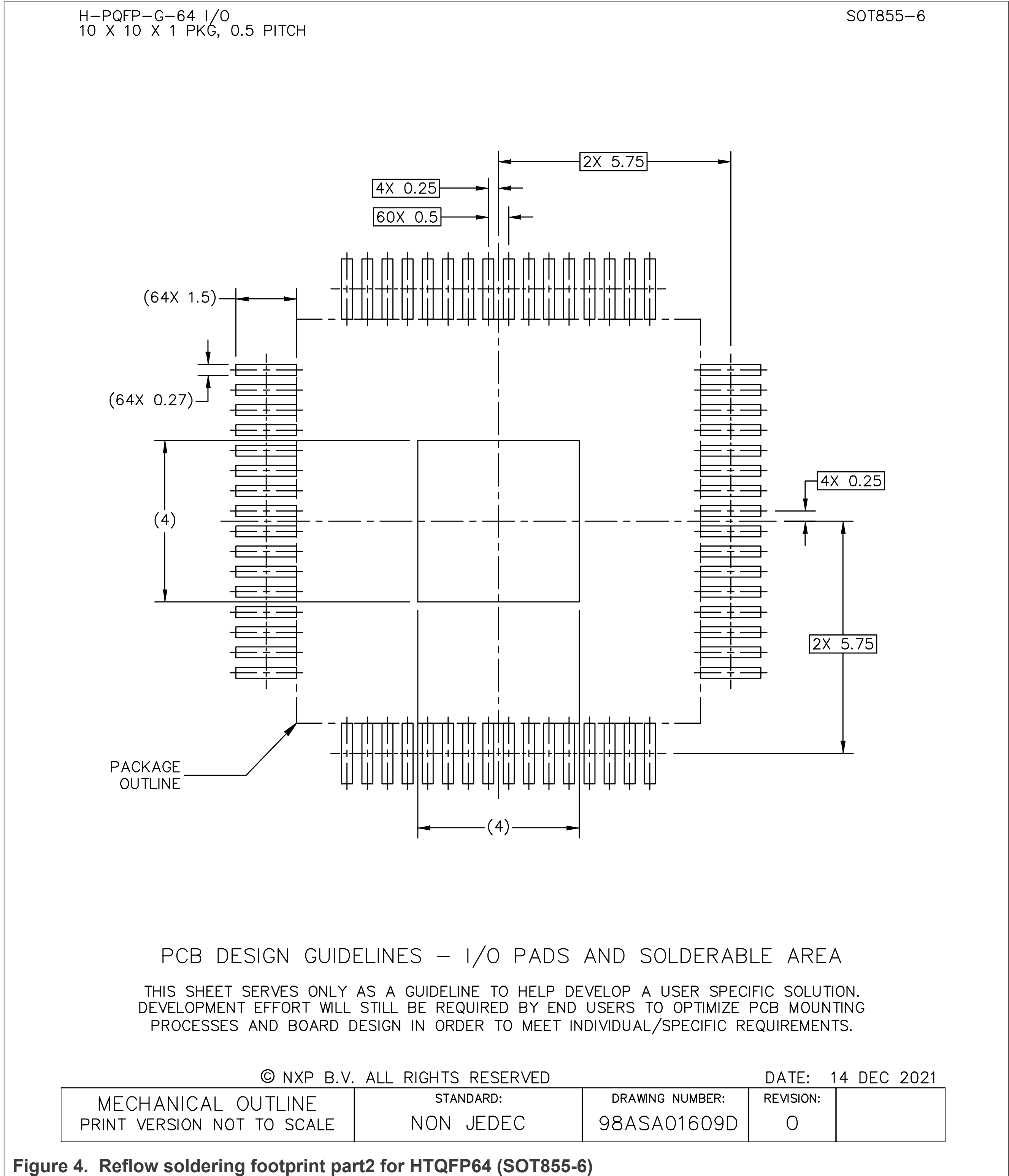

Figure 4. Reflow soldering footprint part2 for HTQFP64 (SOT855-6)

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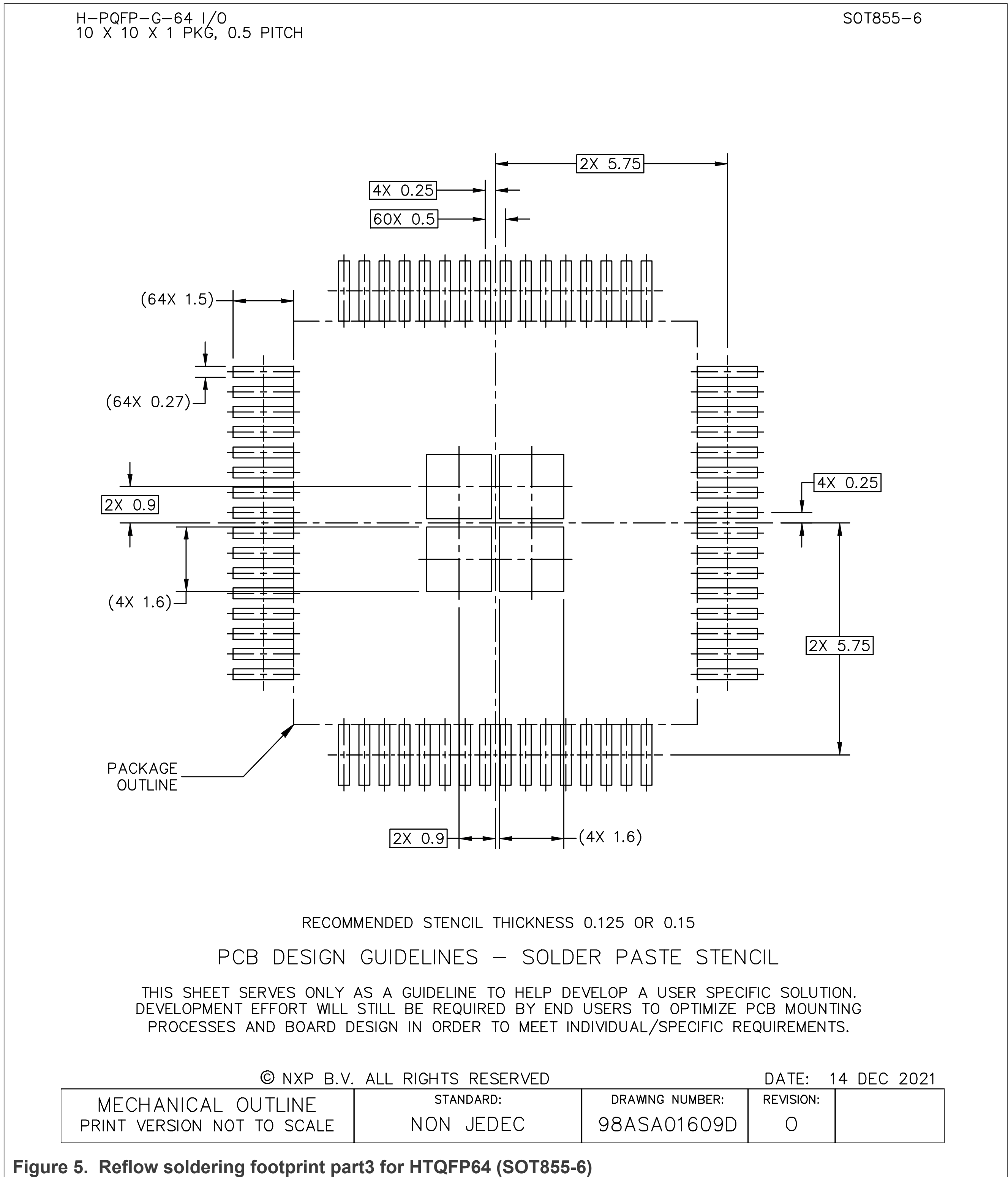

Figure 5. Reflow soldering footprint part3 for HTQFP64 (SOT855-6)

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H–PQFP–G–64 I/O
10 X 10 X 1 PKG, 0.5 PITCH

SOT855–6

NOTES:

1. DIMENSIONS ARE IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.

3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.

4. DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.

5. DIMENSION TO BE DETERMINED AT SEATING PLANE C.

6. THIS DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED THE UPPER LIMIT BY MORE THAN 0.08MM AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD SHALL NOT BE LESS THAN 0.07MM.

7. THIS DIMENSION DOES NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25MM PER SIDE. THIS DIMENSION IS MAXIMUM PLASTIC BODY SIZE DIMENSION INCLUDING MOLD MISMATCH.

8. EXACT SHAPE OF EACH CORNER IS OPTIONAL.

9. HATCHED AREA TO BE KEEP OUT ZONE FOR PCB ROUTING.

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DATE: 14 DEC 2021

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01609D	REVISION: O	

Figure 6. Package outline note HTQFP64 (SOT855-6)

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4 Legal information

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HTQFP64, thermal enhanced thin quad flat package; 64 terminals, 0.5 mm pitch, 10 mm x 10 mm x 1 mm body; exposed die pad

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